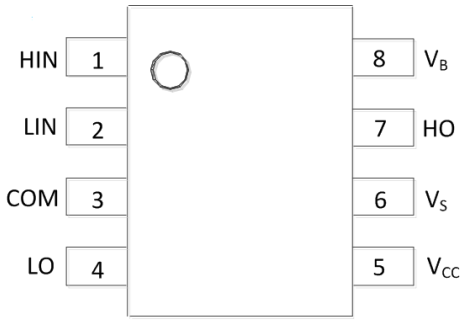
Pin Diagrams

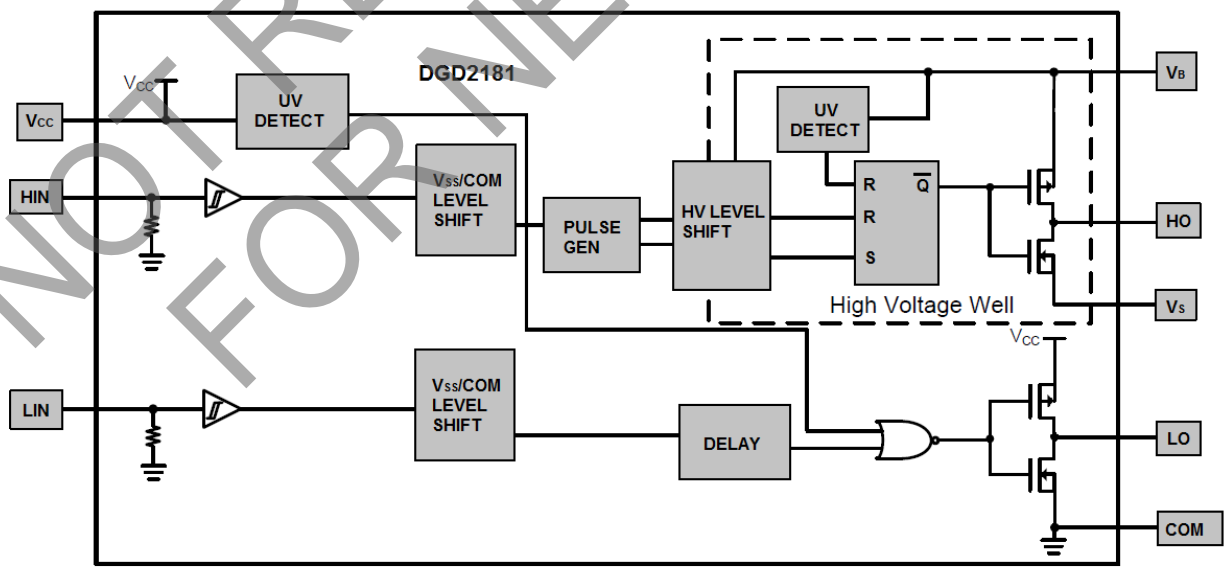


Top View SO-8

Pin Descriptions

Pin Number	Pin Name	Function
1	HIN	Logic input for high-side gate driver output, in phase with HO
2	LIN	Logic input for low-side gate driver output, in phase with LO
3	COM	Low-side and logic return
4	LO	Low-side gate drive output
5	V_{CC}	Low-side and logic fixed supply
6	V_S	High-side floating supply return
7	HO	High-side gate drive output
8	V_B	High-side floating supply

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	V_B	-0.3 to +624	V
High-side Floating Supply Offset Voltage	V_S	V_B-24 to V_B+0.3	V
High-side Floating Output Voltage	V_{HO}	V_S-0.3 to V_B+0.3	V
Offset Supply Voltage Transient	dV_S / dt	50	V/ns
Low-side Fixed Supply Voltage	V_{CC}	-0.3 to +24	V
Low-side Output Voltage	V_{LO}	-0.3 to V_{CC}+0.3	V
Logic Input Voltage (HIN and LIN)	V_{IN}	-0.3 to V_{CC}+0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_D	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Operating Temperature	T_J	+150	°C
Lead Temperature (Soldering, 10s)	T_L	+300	
Storage Temperature Range	T_{STG}	-55 to +150	

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High-side Floating Supply Absolute Voltage	V_B	V_S + 10	V_S + 20	V
High-side Floating Supply Offset Voltage	V_S	(Note 6)	600	V
High-side Floating Output Voltage	V_{HO}	V_S	V_B	V
Low-side Fixed Supply Voltage	V_{CC}	10	20	V
Low-side Output Voltage	V_{LO}	0	V_{CC}	V
Logic Input Voltage (HIN and LIN)	V_{IN}	0	5	V
Ambient Temperature	T_A	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V.

DC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, @T_A = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Logic "1" Input Voltage (Note 8)	V_{IH}	2.5	—	—	V	V_{CC} = 10V to 20V
Logic "0" Input Voltage (Note 8)	V_{IL}	—	—	0.8	V	V_{CC} = 10V to 20V
High Level Output Voltage, V_{BIAS} - V_O	V_{OH}	—	—	1.4	V	I_O = 0mA
Low Level Output Voltage, V_O	V_{OL}	—	—	0.2	V	I_O = 20mA
Offset Supply Leakage Current	I_{LK}	—	—	50	µA	V_B = V_S = 600V
Quiescent V_{BS} Supply Current	I_{BSQ}	20	60	150	µA	V_{IN} = 0V or 5V
Quiescent V_{CC} Supply Current	I_{CCQ}	50	120	240	µA	V_{IN} = 0V or 5V
Logic "1" Input Bias Current	I_{IN+}	—	25	60	µA	V_{IN} = 5V
Logic "0" Input Bias Current	I_{IN-}	—	—	5.0	µA	V_{IN} = 0V
V_{BS} Supply Undervoltage Positive Going Threshold	V_{BSUV+}	8.0	8.9	9.8	V	—
V_{BS} Supply Undervoltage Negative Going Threshold	V_{BSUV-}	7.4	8.2	9.0	V	—
V_{CC} Supply Undervoltage Positive Going Threshold	V_{CCUV+}	8.0	8.9	9.8	V	—
V_{CC} Supply Undervoltage Negative Going Threshold	V_{CCUV-}	7.4	8.2	9.0	V	—
Output High Short Circuit Pulsed Current	I_{O+}	1.4	1.9	—	A	V_O = 0V, PW ≤ 10µs
Output Low Short Circuit Pulsed Current	I_{O-}	1.7	2.3	—	A	V_O = 15V, PW ≤ 10µs

Notes:
7. The V_{IN} and I_{IN} parameters are applicable to the two logic input pins: LIN and HIN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.
8. For optimal operation, it is recommended that the input pulses (HIN and LIN) should have a minimum amplitude of 2.5V with a minimum pulse width of 360ns.

AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Turn-on Propagation Delay	t_{ON}	—	180	270	ns	V_S = 0V
Turn-off Propagation Delay	t_{OFF}	—	220	330	ns	V_S = 0V or 600V
Delay Matching, HO & LO Turn-on/off	t_{DM}	—	—	35	ns	—
Turn-on Rise Time	t_R	—	40	60	ns	V_S = 0V
Turn-off Fall Time	t_F	—	20	35	ns	V_S = 0V

Timing Waveforms

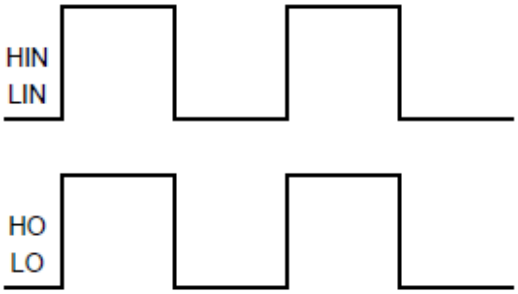


Figure 1. Input / Output Timing Diagram

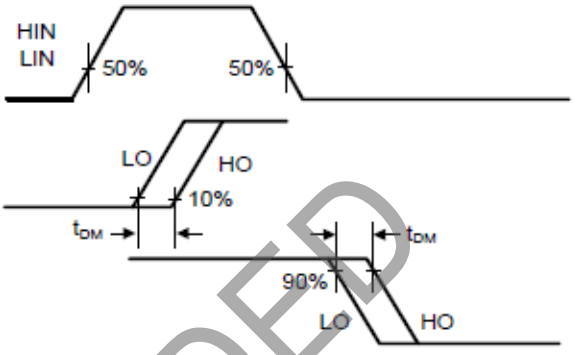


Figure 2. Delay Matching Waveform Definitions

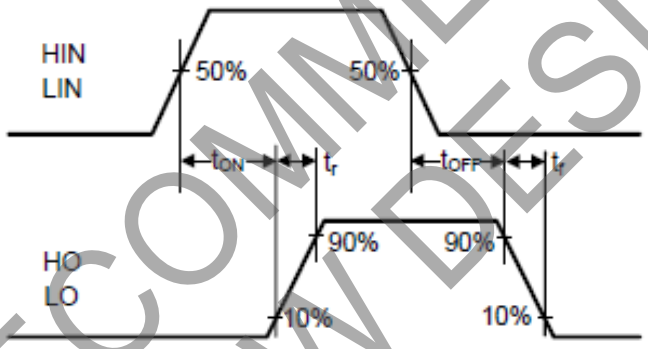


Figure 3. Switching Time Waveform Definitions

Typical Performance Characteristics (@T_A = +25°C, V_{CC} = 15V, unless otherwise specified.)

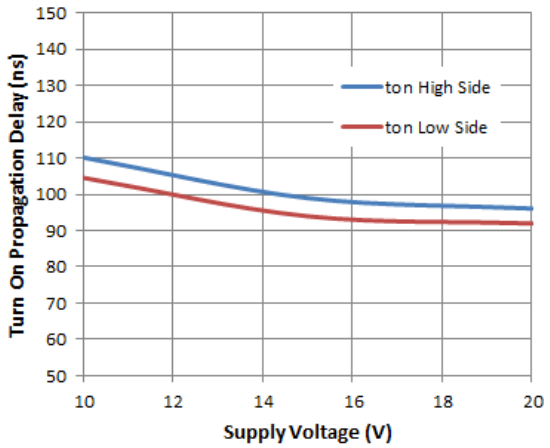


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

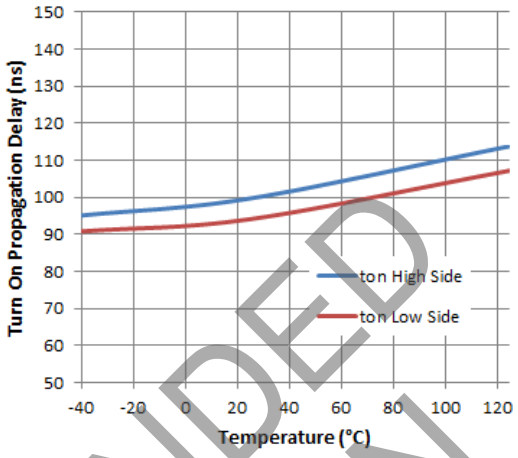


Figure 5. Turn-on Propagation Delay vs. Temperature

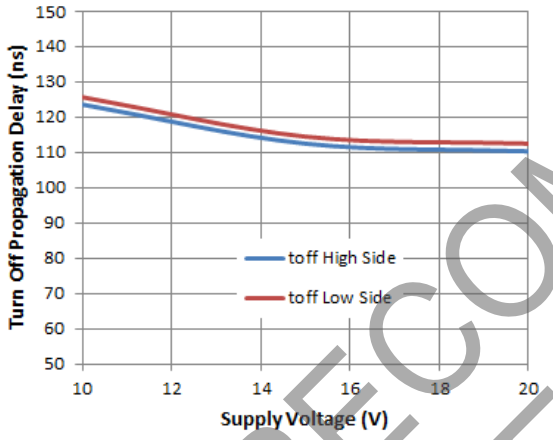


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

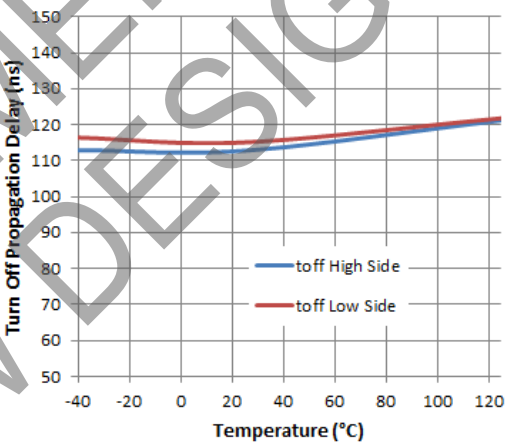


Figure 7. Turn-off Propagation Delay vs. Temperature

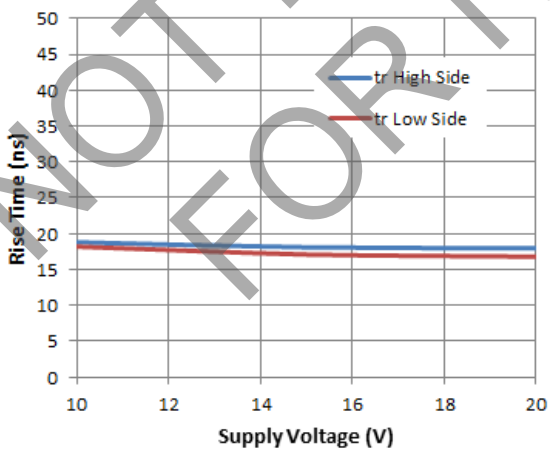


Figure 8. Rise Time vs. Supply Voltage

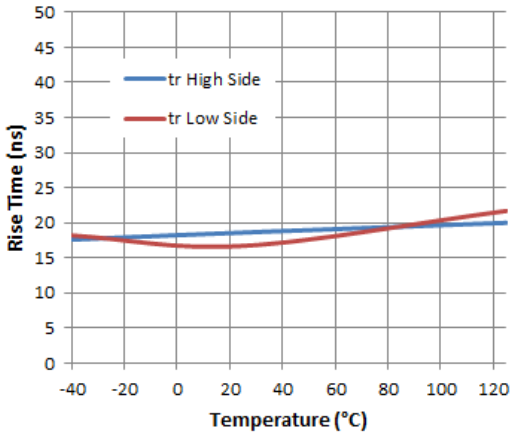


Figure 9. Rise Time vs. Temperature

Typical Performance Characteristics (continued)

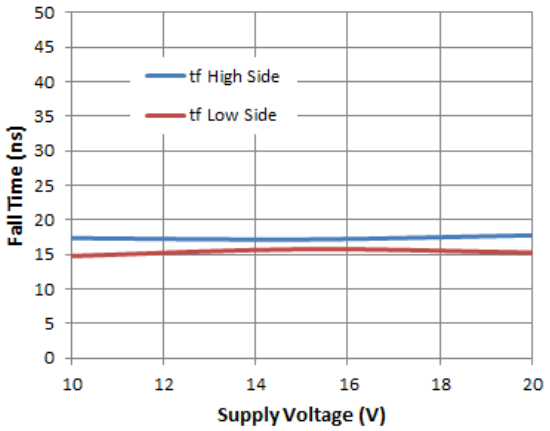


Figure 10. Fall Time vs. Supply Voltage

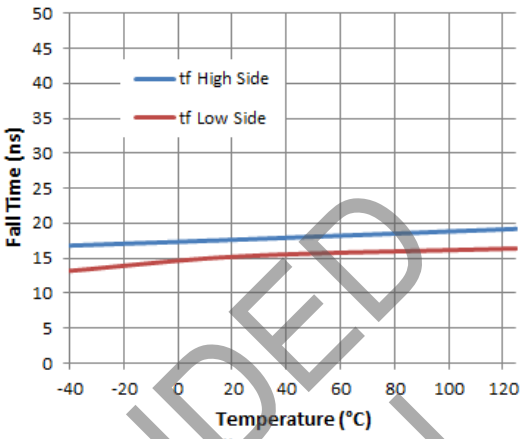


Figure 11. Fall Time vs. Temperature

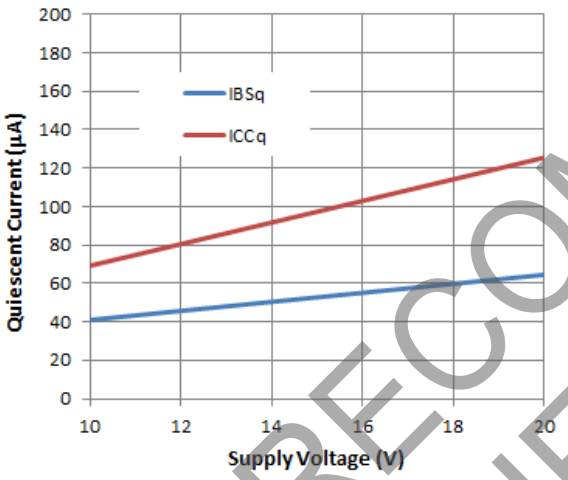


Figure 12. Quiescent Current vs. Supply Voltage

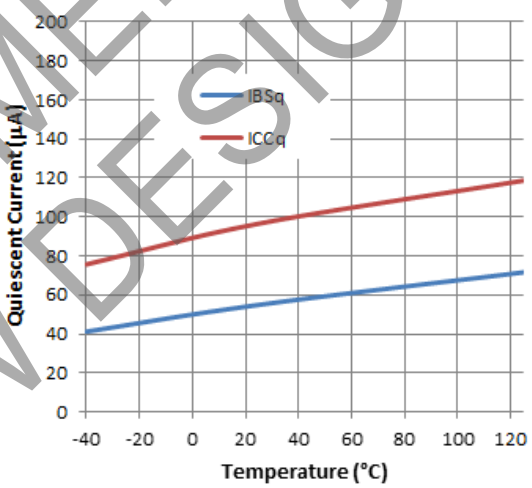


Figure 13. Quiescent Current vs. Temperature

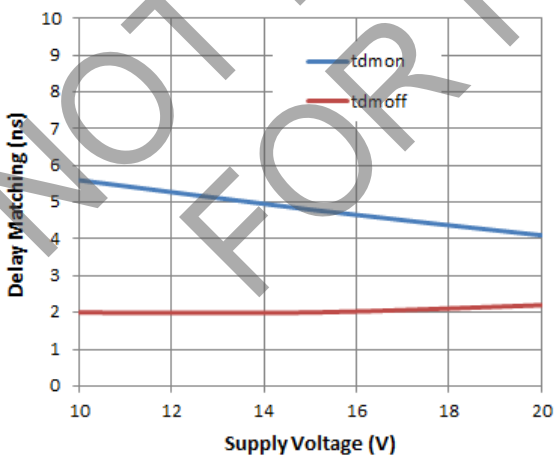


Figure 14. Delay Matching vs. Supply Voltage

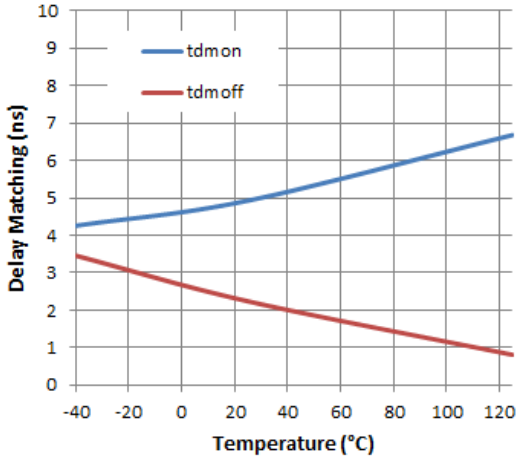


Figure 15. Delay Matching vs. Temperature

Typical Performance Characteristics (continued)

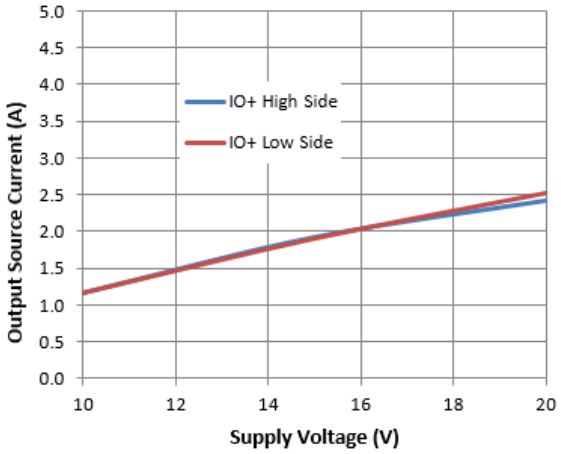


Figure 16. Output Source Current vs. Supply Voltage

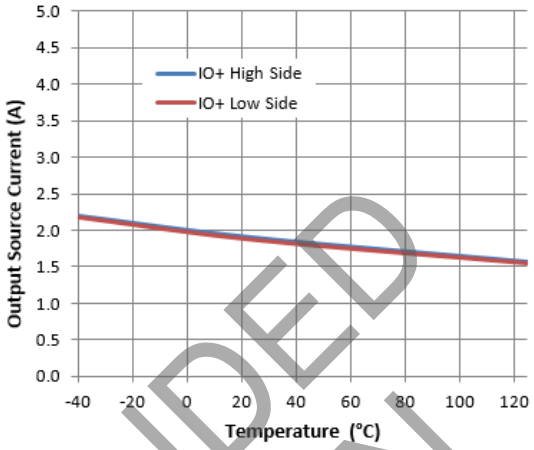


Figure 17. Output Source Current vs. Temperature

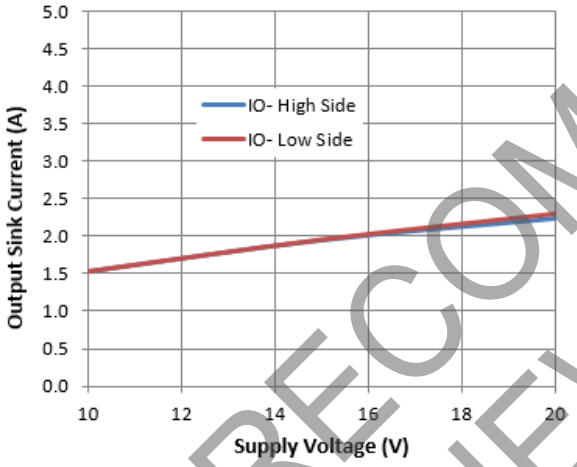


Figure 18. Output Sink Current vs. Supply Voltage

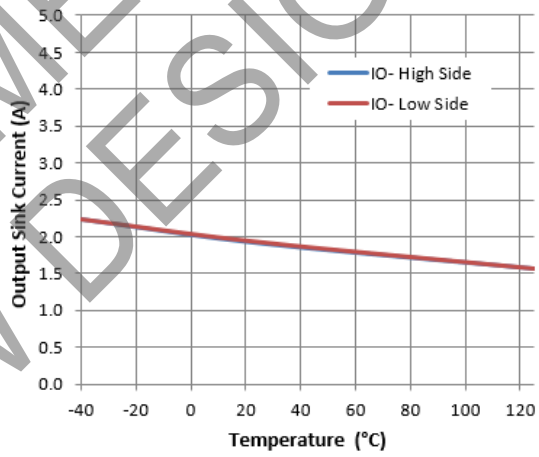


Figure 19. Output Sink Current vs. Temperature

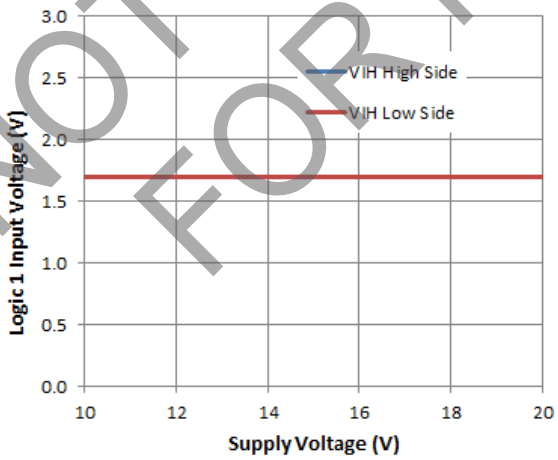


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

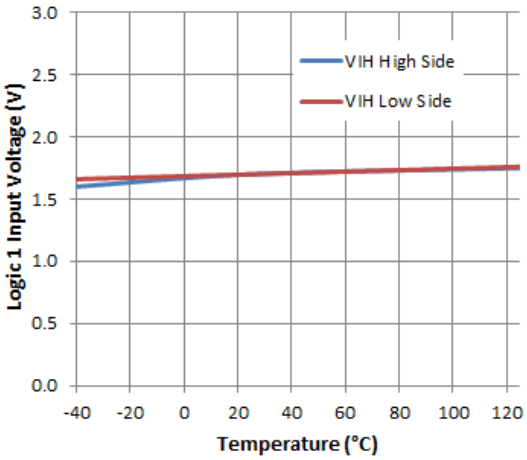


Figure 21. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (continued)

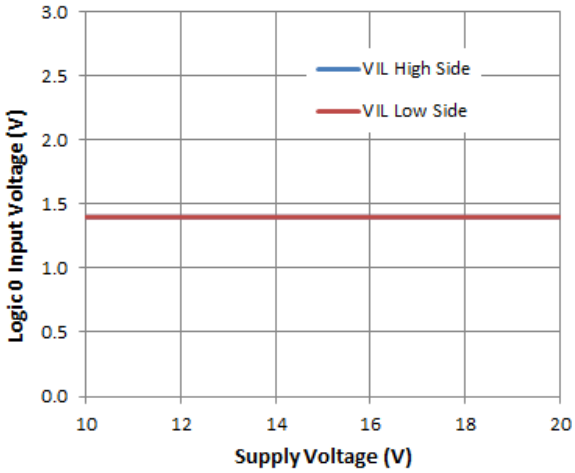


Figure 22. Logic 0 Input Voltage vs. Supply Voltage

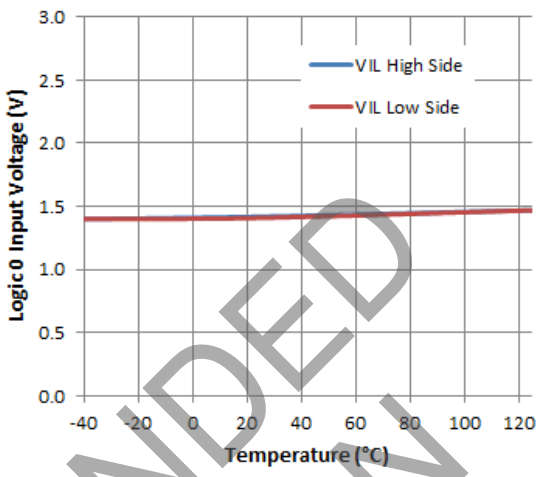


Figure 23. Logic 0 Input Voltage vs. Temperature

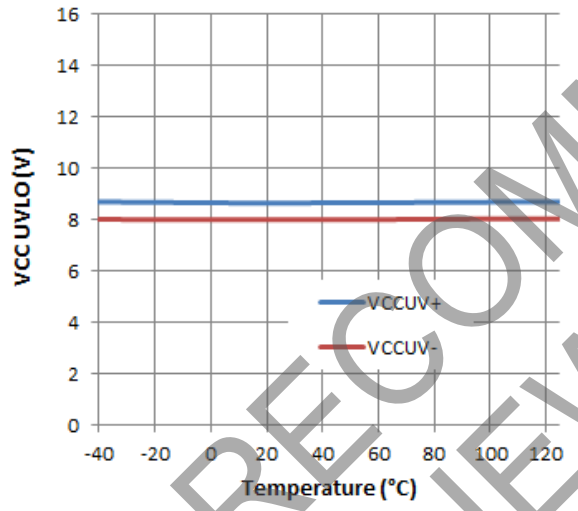


Figure 24. VCC UVLO vs. Temperature

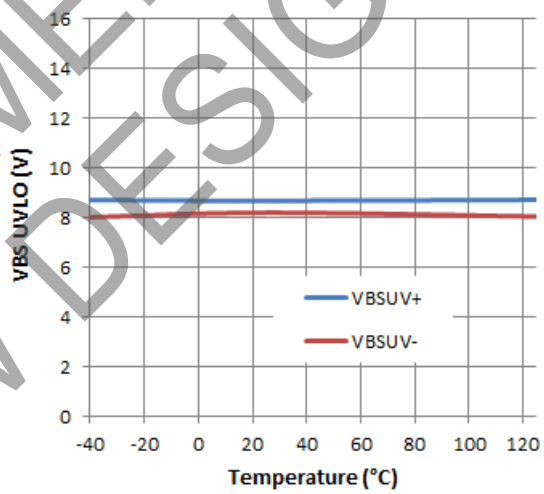


Figure 25. VBS UVLO vs. Temperature

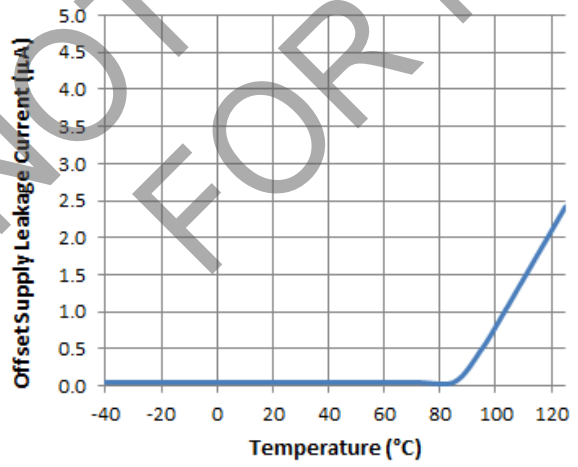
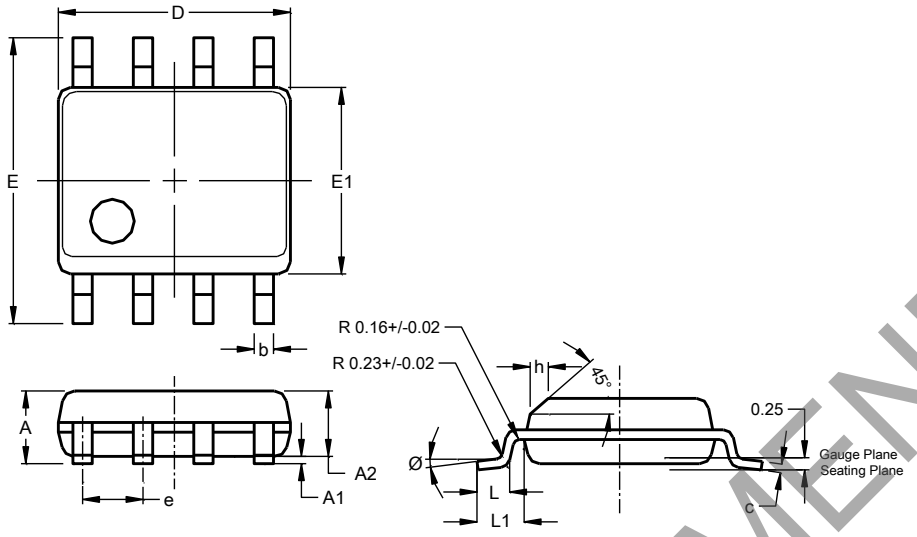


Figure 26. Offset Supply Leakage Current vs. Temperature

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)

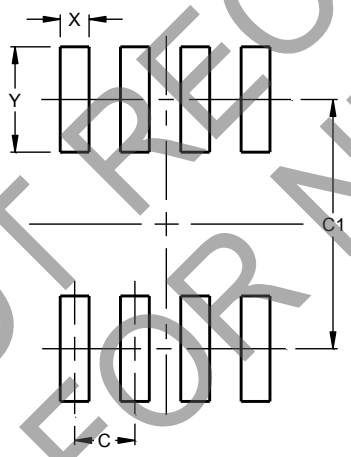


SO-8 (Type TH)			
Dim	**Min**	**Max**	**Typ**
A	1.35	1.75	--
A1	0.10	0.25	--
A2	--	--	1.45
b	0.35	0.51	--
c	0.190	0.248	--
D	4.80	5.00	4.90
E	5.80	6.20	6.00
E1	3.80	4.00	3.90
e	--	--	1.27
h	0.25	0.50	--
L	0.41	1.27	--
L1	--	--	1.04
Ø	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Type TH)



Dimensions	Value (in mm)
C	1.27
C1	5.20
X	0.60
Y	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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